

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB20N03
Package Type :	PDFNWB3.3x3.3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	6.7673%
Lead Frame	Copper	7440-50-8	92.46%	36.935%
	Iron	7439-89-6	2.50%	
	Lead	7439-92-1	0.01%	
	Phosphorus	7723-14-0	0.02%	
	Zinc	7440-66-6	0.02%	
	Silver	7440-22-4	5.00%	
Die Attach	Tin	7440-31-5	4.70%	15.738%
	Lead	7439-92-1	85.00%	
	Silver	7440-22-4	2.30%	
	polyglycol	9038-95-3	5.00%	
	carboxlic	67762-36-1	0.50%	
	Modified	61788-85-0	2.50%	
Wire	Cu	7440-50-8	100.00%	5.5427%
Mold Compound	Silica	60676-86-0	85.00%	29.607%
	Epoxy Resin	85954-11-6	8.50%	
	Phenol Resin	29690-82-2	6.00%	
	Carbon Black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	100.00%	5.4099%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.